

TECHNOLOGIES

Item	Technical Specification	
	Standard	Advanced
Board thickness	Maximum (mm)	7 10
Panel size	Maximum (mm)	600x730 650x1120
Layer count	Maximum rigid boards	32 76
	Maximum flex boards	14 20
Mechanical drilling	Maximum aspect ratio	1:14 1:20
	Minimum drill diameter (mm)	0.15 0.1
	Hole accuracy (mic)	± 38 ± 30
Laser drilling	Minimum laser diameter (mic)	75 60
	Aspect ratio microvia	1:0.8 1:1
Lines/spaces	Minimum outer layer (mic)	75/75 63.5/63.5
	Minimum inner layer (mic)	63.5/63.5 50/50
Minimum core thickness	Minimum core thickness (mic)	50
Impedance control	Accuracy	± 10% ± 5%
Final finishing	C.O.B. gold finish	Yes
	Hard gold	Yes
	OSP	Yes
	ENIG	Yes
	HAL	Yes
	LF HAL	Yes
	Immersion tin	Yes
	Immersion silver	Yes

Special Technologies

- Flex/rigid-flex boards
- High-layer counts
- Blind and buried vias
- Via-in-pad and hole plugging
- HDIs
- Backdrilling
- High-speed boards
- High-frequency and microwave PCBs
- Backplanes
- Buried resistors and capacitors
- Heavy copper PCBs, heat sinks
- IMS (aluminum copper clad circuits)

Certifications and Standards

- ISO 9001:2000
- SO/TS 16949
- ISO 14001
- AS9100
- IPC Class 3
- UL V0, RoHS, REACH
- Mil-PRF-55110
- Mil-P-31032
- NADCAP
- Highly Accelerated Thermal Shock (HATS™)